

ASSIGNMENT

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PARTIES TO THE ASSIGNMENT:

INVENTORS:

Klaus Florian Schuegraf

Randhir P. S. Thakur

ASSIGNEE:

Micron Technology, Inc.
Corporation of the State of Delaware
8000 South Federal Way
Boise, Idaho 83706-9632

BACKGROUND OF THIS ASSIGNMENT:

INVENTORS have conceived certain new and useful inventions disclosed in a United States patent application titled Methods For Forming Wordlines, Transistor Gates, And Conductive Interconnects, And Wordline, Transistor Gate, and Conductive Interconnect Structures.

MICRON TECHNOLOGY, INC. (hereinafter referred to as "ASSIGNEE") desires to acquire the entire right, title and interest in said inventions and with respect to any Letters Patent that may be granted with respect to the inventions in both the United States and in all foreign countries.

THE PARTIES AGREE AS FOLLOWS:

21 In consideration of good and valuable consideration, the receipt
22 sufficiency and adequacy of which is hereby acknowledged, INVENTORS
23 hereby sell, assign and transfer to ASSIGNEE the entire right, title and

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1 interest in the above-identified application executed currently with this
2 assignment and to any reissues, renewals, divisions or continuations thereof,
3 and hereby authorizes the Commissioner of Patents and Trademarks to issue
4 such Letters Patent to ASSIGNEE for the sole use of ASSIGNEE, its
5 successors or assigns.

6 INVENTORS further agree to execute, at the request and expense of
7 ASSIGNEE such other formal documents as may be required to fully convey
8 the interest transferred herein and will similarly execute any application papers
9 required for the filing of any division, continuation, renewal or reissue of the
10 patent application or resulting Letters Patent; and will generally do everything
11 necessary or desirable to obtain and enforce proper protection for the
12 inventions assigned hereby.

13 INVENTORS further assign to ASSIGNEE the whole right, title and
14 interest in the inventions disclosed in the application throughout all countries
15 foreign to the United States. ASSIGNEE is hereby authorized to apply for
16 patents relating to the inventions in its own name in countries where such
17 procedure is proper; to claim the benefit of the International Convention; to
18 file and prosecute International Applications relating to the inventions under
19 the Patent Cooperation Treaty; and to file and prosecute applications relating
20 to the inventions under the European Patent Convention. INVENTORS agree
21 to execute applications relating to the inventions in those countries and under
22 those conventions where it is necessary that the same be executed by the
23 inventor, and to execute assignments of such applications and the resulting

1 Letters Patent to ASSIGNEE as well as all other necessary papers in relation
2 to such applications and Letters Patent.

3 INVENTORS further warrant and covenant that no assignment, grant,
4 mortgage, license or other agreement affecting the rights and property herein
5 conveyed has been or will be made to others by the undersigned, and that the
6 full rights to convey the same as herein expressed is possessed by the
7 undersigned.

8 To be binding on the heirs, assigns, representatives and successors of
9 the undersigned and extend to the successors, assigns and nominees of the
10 Assignees.

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12 (Signature) _____ Date: _____
13 Klaus Florian Schuegraf

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2 (Signature) Randhir P S Thakur Date: 5/24/93
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